Electronic Patent Application Fee Transmittal							
Application Number:	10811152						
Filing Date:	29-Mar-2004						
Title of Invention:	METHOD OF FORMING INTER-DIELECTRIC LAYER IN SEMICONDUCTOR DEVICE						
First Named Inventor/Applicant Name:	Ga Won Lee						
Filer:	Yoon Ham/james rhee						
Attorney Docket Number:	123034-05004767						
Filed as Large Entity							
Utility Filing Fees							
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:							
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:							
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Utility Appl issue fee		1501	1	1400	1400		
Publ. Fee- early, voluntary, or normal		1504	1	300	300		

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
	Total in USD (\$)			1700